

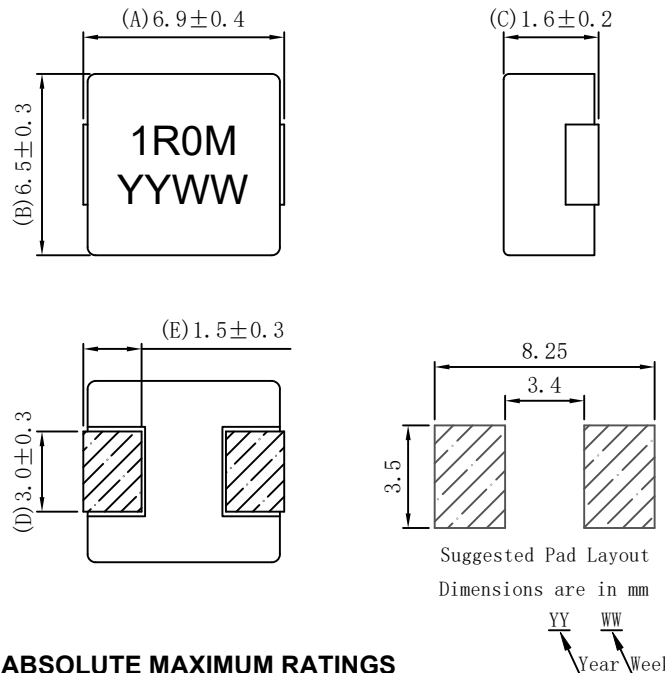
FEATURES

- RoHS compliant,UL94V-0
- Small size (7.3*6.8mm Max),low profile(Height:1.8mm Max)
- Inductance range from 0.10uH to 15.0uH
- Surface mount design
- Magnetic shield construction
- Ultra low buzz noise due to composite construction
- Handle transient current spikes without saturation
- Excellent temperature stability for inductance and saturation
- Tape & reel packing
- Solder profile acc.J-STD-020D

APPLICATIONS

- Low profile ,high current power supplies
- DC/DC converters
- Battery powered devices
- PDA/notebook/desktop/server applications

Part number	Inductance (μ H \pm 20%)	DCR (m Ω)@25 $^{\circ}$ C		Irms (A)	Isat (A)
		TYP.	MAX.		
MHA0718NSGR10M	0.10	2.00	2.50	21.00	45.00
MHA0718NSGR15M	0.15	2.85	3.20	20.00	31.00
MHA0718NSGR22M	0.22	4.50	5.20	14.00	29.00
MHA0718NSGR33M	0.33	5.20	6.80	12.00	22.00
MHA0718NSGR47M	0.47	7.30	8.40	11.00	18.00
MHA0718NSGR68M	0.68	10.80	12.70	9.00	17.00
MHA0718NSG1R0M	1.00	14.50	17.00	7.00	12.00
MHA0718NSG1R5M	1.50	20.00	26.00	6.50	10.00
MHA0718NSG2R0M	2.00	28.00	32.00	6.00	8.00
MHA0718NSG2R2M	2.20	31.00	35.00	6.00	8.00
MHA0718NSG3R3M	3.30	56.00	60.00	3.50	7.00
MHA0718NSG4R7M	4.70	68.00	70.00	3.50	5.00
MHA0718NSG6R8M	6.80	101.0	110.0	2.80	3.50
MHA0718NSG8R2M	8.20	120.0	135.0	2.50	3.00
MHA0718NSG100M	10.0	140.0	155.0	2.30	2.50
MHA0718NSG150M	15.0	215.0	250.0	1.80	2.20



ABSOLUTE MAXIMUM RATINGS

Operating temperature rang -55 $^{\circ}$ C to +125 $^{\circ}$ C
(Including coil' self temperature rise)
Storage temperature rang -55 $^{\circ}$ C to +125 $^{\circ}$ C

SOLDERING INFORMATION

Peak reflow temperature 250 $^{\circ}$ C
Pin finish tin

PACKAGING INFORMATION

Tape&Reel 2000pcs per reel
Weight 0.44g/pcs

Notes

1. Electrical specification at 25 $^{\circ}$ C.
2. Inductance tested at 100 kHz, 0.25Vrms.
3. Irms is the current that caused a approximate 40 $^{\circ}$ C temperature rise from 25 $^{\circ}$ C ambient.
4. Isat is the DC current at which inductance drop approximately 30% from its value without current.
5. The part temperature(ambient + temp.rise) should not exceed 125 $^{\circ}$ C under worst case operating conditions.Circuit design,component placement, PWB trace size and thickness,airflow and other cooling provisions all affect the part temperature.Part temperature should be verified in the end application.